

WHAT IS CLAIMED IS:

1. A non-volatile semiconductor memory device comprising:

a memory cell array having a plurality of non-volatile memory cells each having three or more threshold voltage levels;

word lines, bit lines and source lines connected to said memory cells;

a row decoder configured to select one of said word lines; and

a column decoder configured to select one of said bit lines,

wherein when said three threshold voltage levels are given by V_{t1} , V_{t2} and V_{t3} ($V_{t1} < V_{t2} < V_{t3}$), respectively, the following steps (1) to (5) are executed to carry out a program operation,

(1) loading program data,

(2) programming for said memory cells to be given by the threshold voltage V_{t2} being accomplished by a first gate voltage,

(3) detecting whether said memory cells have the threshold voltage V_{t2} , and carrying out said step (2) using a second gate voltage higher than said first gate voltage when said memory cells do not have the threshold voltage V_{t2} , followed by a next step (4) when said memory cells have the threshold voltage V_{t2} ,

(4) programming for said memory cells to be given by the threshold voltage V_{t3} being carried out by a third gate voltage having a value equal to or higher than a maximum value of a program gate voltage of said memory cells to be given by the threshold voltage V_{t2} , and

(5) detecting whether said memory cells have the threshold voltage V_{t3} , and re-executing said step (4) when said memory cells do not have the threshold voltage V_{t3} , and finishing said program operation when said memory cells have the threshold voltage V_{t3} .

2. A non-volatile semiconductor memory device comprising:

a memory cell array having a plurality of non-volatile memory cells each having three or more threshold voltage levels;

word lines, bit lines and source lines connected to said memory cells;

a row decoder configured to select one of said word lines; and

a column decoder configured to select one of said bit lines,

wherein when said three threshold voltage levels are given by V_{t1} , V_{t2} and V_{t3} ($V_{t1} < V_{t2} < V_{t3}$), respectively, the following steps (1) to (5) are executed to carry out a program operation,

(1) loading program data,

(2) programming for said memory cells to be given by the threshold voltage V_{t3} being accomplished by a voltage value equal to or higher than a maximum value of a program gate voltage of said memory cells to be given by the threshold voltage V_{t2} ,

(3) detecting whether said memory cells have the threshold voltage V_{t3} , and re-executing said step (2) when said memory cells do not have the threshold voltage V_{t2} , followed by a next step (4) when said memory cells have the threshold voltage V_{t2} ,

(4) programming for said memory cells to be given by the threshold voltage V_{t2} being carried out by a first gate voltage, and

(5) detecting whether said memory cells have the threshold voltage V_{t2} , and executing said step(4) using a second gate voltage higher than said first gate voltage when said memory cells do not have the threshold voltage V_{t2} , while finishing said program operation when said memory cells have the threshold voltage V_{t2} .

3. A non-volatile semiconductor memory device comprising:

a memory cell array having a plurality of non-volatile memory cells each having four or more threshold voltage levels;

word lines, bit lines and source lines connected to said memory cells;

a row decoder configured to select one of said word lines; and

a column decoder configured to select one of said bit lines,

wherein when said four threshold voltage levels are given by V_{t1} , V_{t2} , V_{t3} and V_{t4} ($V_{t1} < V_{t2} < V_{t3} < V_{t4}$), respectively, the following steps (1) to (5) are executed to carry out a program operation,

(1) loading program data,

(2) programs for said memory cells to be given by the threshold voltage V_{t2} and for said memory cells to be given by the threshold voltage V_{t3} being accomplished by a first gate voltage,

(3) detecting whether the threshold voltages of said memory cells have V_{t2} and V_{t3} , respectively, and re-executing said step (2) when said memory cells do not have the threshold

voltages V_{t2} and V_{t3} , followed by a next step (4) when said memory cells have the threshold voltages V_{t2} and V_{t3} ,

(4) programming for said memory cells to be given by the threshold voltage V_{t4} being carried out by a voltage value equal to or higher than a maximum value of a program gate voltage of said memory cells to be given by one of V_{t2} and V_{t3} , and

(5) detecting whether said memory cells given by V_{t4} have the threshold voltage of V_{t4} , and re-executing said step (4) when said memory cells do not have the threshold voltage V_{t4} , while finishing said program operation when said memory cells have the threshold voltage V_{t4} .

4. A non-volatile semiconductor memory device comprising:

a memory cell array having a plurality of non-volatile memory cells each having four or more threshold voltage levels;

word lines, bit lines and source lines connected to said memory cells;

a row decoder configured to select one of said word lines; and

a column decoder configured to select one of said bit lines,

wherein when said four threshold voltage levels are given by V_{t1} , V_{t2} , V_{t3} and V_{t4} ($V_{t1} < V_{t2} < V_{t3} < V_{t4}$), respectively, the following steps (1) to (5) are executed to carry out a program operation,

(1) loading program data,

(2) programming for said memory cells to be given by the threshold voltage V_{t4} being accomplished by a value which is equal to or higher than a maximum value of a program gate

voltage of said memory cells to be given by one of the threshold voltages V_{t2} and V_{t3} ,

(3) detecting whether the threshold voltage of said memory cells to be given by the threshold voltage V_{t4} have the threshold voltage V_{t4} , and re-executing said step (2) when said memory cells do not have the threshold voltage V_{t4} , followed by a next step (4) when said memory cells have the threshold voltage V_{t4} ,

(4) programming for said memory cells to be given by the threshold voltages V_{t2} and V_{t3} being carried out by said first gate voltage, and

(5) detecting whether said memory cells given by the threshold voltages V_{t2} and V_{t3} have said threshold voltages of V_{t2} and V_{t3} , respectively, and re-executing said step (2) when said memory cells do not have the threshold voltages V_{t2} and V_{t3} , respectively, while finishing said program operation when said memory cells have the threshold voltages V_{t2} and V_{t3} .